

The MPC942 is a 1:18 low voltage clock distribution chip with 2.5V or 3.3V LVCMOS output capabilities. The device is offered in two versions; the MPC942C has an LVCMOS input clock while the MPC942P has a LVPECL input clock. The 18 outputs are 2.5V or 3.3V LVCMOS compatible and feature the drive strength to drive 50 Ω series or parallel terminated transmission lines. With output-to-output skews of 200ps, the MPC942 is ideal as a clock distribution chip for the most demanding of synchronous systems. The 2.5V outputs also make the device ideal for supplying clocks for a high performance Pentium II™ microprocessor based design.

- LVCMOS/LVTTL Clock Input
- 2.5V LVCMOS Outputs for Pentium II Microprocessor Support
- 150ps Maximum Targeted Output-to-Output Skew
- Maximum Output Frequency of 250MHz @ 3.3 V_{CC}
- 32-Lead TQFP Packaging
- Single 3.3V or 2.5V Supply
- **NRND – Not Recommend for New Designs**

With a low output impedance ($\approx 12\Omega$), in both the HIGH and LOW logic states, the output buffers of the MPC942 are ideal for driving series terminated transmission lines. With an output impedance of 12 Ω the MPC942 can drive two series terminated transmission lines from each output. This capability gives the MPC942 an effective fanout of 1:36. The MPC942 provides enough copies of low skew clocks for most high performance synchronous systems.

The LVCMOS/LVTTL input of the MPC942C provides a more standard LVCMOS interface. The OE pins will place the outputs into a high impedance state. The OE pin has an internal pullup resistor.

The MPC942 is a single supply device. The V_{CC} power pins require either 2.5V or 3.3V. The 32-lead TQFP package was chosen to optimize performance, board space and cost of the device. The 32-lead TQFP has a 7x7mm body size with a conservative 0.8mm pin spacing.

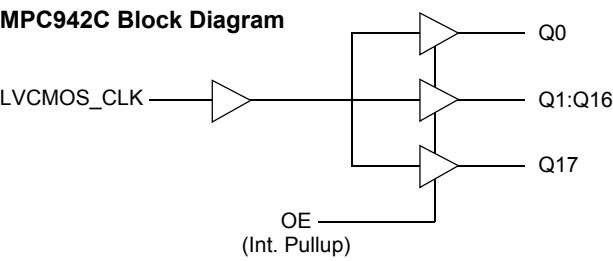
MPC942C

LOW VOLTAGE 1:18 CLOCK DISTRIBUTION CHIP



AC SUFFIX
32-LEAD TQFP PACKAGE
Pb-FREE PACKAGE
CASE 873A-03

LOGIC DIAGRAM



FUNCTION TABLE

OE	Output
0	HIGH IMPEDANCE OUTPUTS ENABLED
1	

Pinout: 32-Lead (Top View)

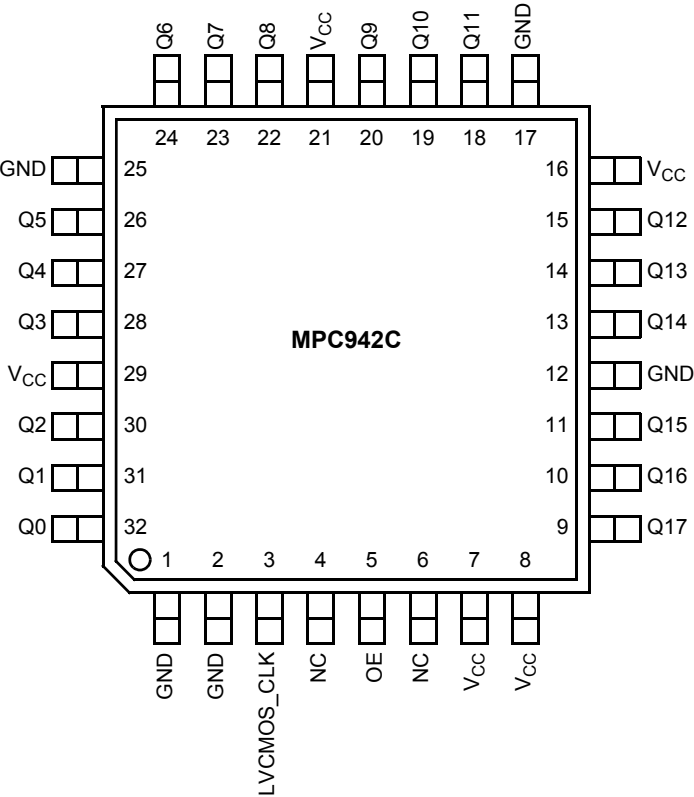


Table 1. Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	-0.3	3.6	V
V _I	Input Voltage	-0.3	V _{CC} + 0.3	V
I _{IN}	Input Current		±20	mA
T _{Stor}	Storage Temperature Range	-40	125	°C

Table 2. DC Characteristics ($T_A = 0^\circ$ to 70°C , $V_{CCI} = 2.5\text{V} \pm 5\%$, $V_{CCO} = 2.5\text{V} \pm 5\%$)

Symbol	Characteristic	Min	Typ	Max	Unit	Condition
V_{IH}	Input HIGH Voltage	2.0		V_{CCI}	V	
V_{IL}	Input LOW Voltage			0.8	V	
V_{OH}	Output HIGH Voltage	2.0			V	$I_{OH} = -16\text{ mA}$
V_{OL}	Output LOW Voltage			0.5	V	$I_{OL} = 16\text{ mA}$
I_{IN}	Input Current			± 200	μA	
C_{IN}	Input Capacitance		4.0		pF	
C_{PD}	Power Dissipation Capacitance		14		pF	Per Output
Z_{OUT}	Output Impedance		12		Ω	
I_{CC}	Maximum Quiescent Supply Current		0.5		mA	

Table 3. AC Characteristics ($T_A = 0^\circ$ to 70°C , $V_{CCI} = 2.5\text{V} \pm 5\%$, $V_{CCO} = 2.5\text{V} \pm 5\%$)

Symbol	Characteristic	Min	Typ	Max	Unit	Condition
F_{max}	Maximum Frequency			200	MHz	
t_{PLH}	Propagation Delay	1.5		2.8	ns	
$t_{sk(o)}$	Output-to-Output Skew			200	ps	
$t_{sk(pr)}$	Part-to-Part Skew			1.3	ns	Notes 1, 2
$t_{sk(pr)}$	Part-to-Part Skew			600	ps	Notes 1, 3
d_t	Duty Cycle	45		55	%	
t_r, t_f	Output Rise/Fall Time	0.2		1.0	ns	

Table 4. DC Characteristics ($T_A = 0^\circ$ to 70°C , $V_{CCI} = 3.3\text{V} \pm 5\%$, $V_{CCO} = 3.3\text{V} \pm 5\%$)

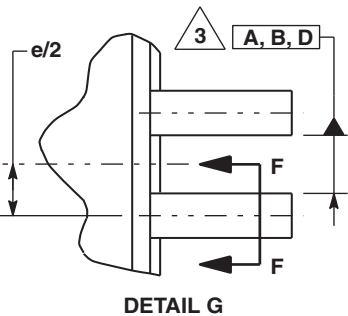
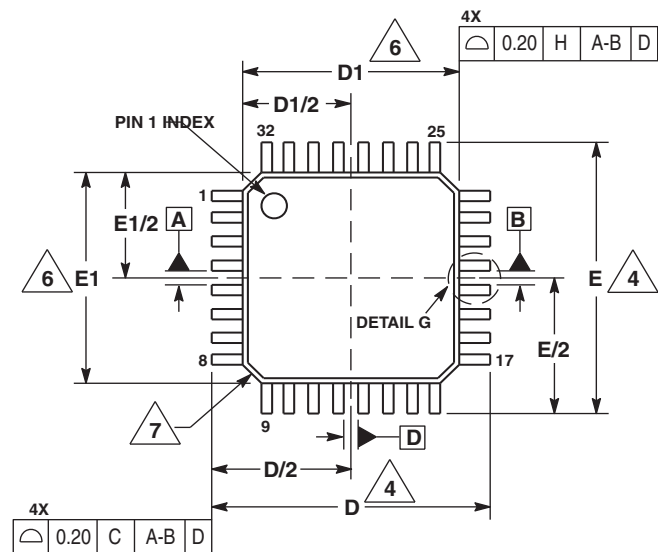
Symbol	Characteristic	Min	Typ	Max	Unit	Condition
V_{IH}	Input HIGH Voltage	2.4		V_{CCI}	V	
V_{IL}	Input LOW Voltage			0.8	V	
V_{OH}	Output HIGH Voltage	2.4			V	$I_{OH} = -20\text{ mA}$
V_{OL}	Output LOW Voltage			0.5	V	$I_{OL} = 20\text{ mA}$
I_{IN}	Input Current			± 200	μA	
C_{IN}	Input Capacitance		4.0		pF	
C_{PD}	Power Dissipation Capacitance		14		pF	Per Output
Z_{OUT}	Output Impedance		12		Ω	
I_{CC}	Maximum Quiescent Supply Current		0.5		mA	

Table 5. AC Characteristics ($T_A = 0^\circ$ to 70°C , $V_{CCI} = 3.3\text{V} \pm 5\%$, $V_{CCO} = 3.3\text{V} \pm 5\%$)

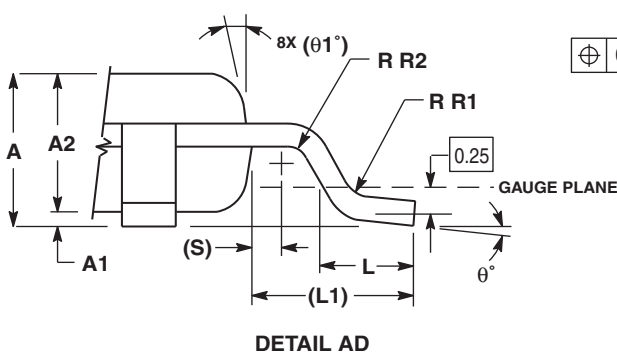
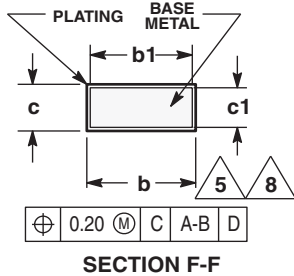
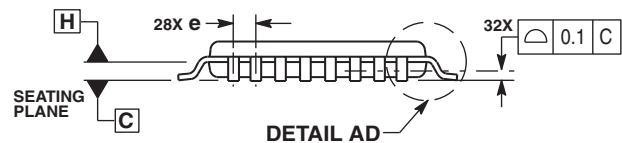
Symbol	Characteristic	Min	Typ	Max	Unit	Condition
F_{max}	Maximum Frequency			250	MHz	
t_{PLH}	Propagation Delay	1.3		2.3	ns	Note 1
$t_{sk(o)}$	Output-to-Output Skew			200	ps	
$t_{sk(pr)}$	Part-to-Part Skew			1.0	ns	Notes 1, 2
$t_{sk(pr)}$	Part-to-Part Skew			500	ps	Notes 1, 3
d_t	Duty Cycle	45		55	%	
t_r, t_f	Output Rise/Fall Time	0.2		1.0	ns	

1. Tested using standard input levels, production tested @ 133 MHz.
2. Across temperature and voltage ranges, includes output skew.
3. For a specific temperature and voltage, includes output skew.

PACKAGE DIMENSIONS



- NOTES:
- 1. DIMENSIONS ARE IN MILLIMETERS.
 - 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 - 3. DATUMS A, B, AND D TO BE DETERMINED AT DATUM PLANE H.
 - 4. DIMENSIONS D AND E TO BE DETERMINED AT SEATING PLANE C.
 - 5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM b DIMENSION BY MORE THAN 0.08-mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION: 0.07-mm.
 - 6. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25-mm PER SIDE. D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
 - 7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
 - 8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1-mm AND 0.25-mm FROM THE LEAD TIP.



MILLIMETERS		
DIM	MIN	MAX
A	1.40	1.60
A1	0.05	0.15
A2	1.35	1.45
b	0.30	0.45
b1	0.30	0.40
c	0.09	0.20
c1	0.09	0.16
D	9.00 BSC	
D1	7.00 BSC	
e	0.80 BSC	
E	9.00 BSC	
E1	7.00 BSC	
L	0.50	0.70
L1	1.00 REF	
q	0°	7°
q1	12° REF	
R1	0.08	0.20
R2	0.08	---
S	0.20 REF	

CASE 873A-03
ISSUE B
LQFP PLASTIC PACKAGE

Revision History Sheet

Rev	Table	Page	Description of Change	Date
2		1	NRND – Not Recommend for New Designs	1/8/13

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